

# 2.1MHz, 3 CHs, Step-Down Converter with I<sup>2</sup>C Interface

### **General Description**

The RT5800 is a multi-phase, programmable power management IC, integrated with four high efficient, synchronous step-down converter cores. The RT5800 can be 2 + 2 and 2 + 1 + 1 output by OTP. It also features wide output voltage range and the capability to configure the corresponding power stages, which make the device optimized to meet power management requirements for low-power processors, such as core power for CPUs and GPUs. The RT5800 supports many programmable functions including voltage level, slew rate of voltage change, and slew rate of soft-start via an I<sup>2</sup>C interface capable of operating up to 3.4MHz. The RT5800 also supports remote-sense function to get accurate output voltage at large loading. Moreover, the device has interrupt and fault-detection function to report error status. The RT5800 is available in a WQFN-30L 4.5x5 (FC) package.

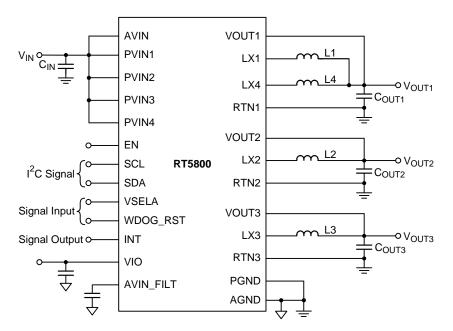
### **Applications**

Automotive Systems

#### **Features**

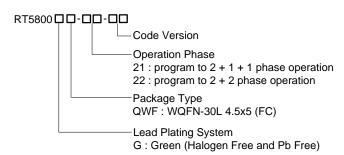
- FMEA Compliant PinOut
- 2 + 2 / 2 + 1 + 1 Phase Output
- Input Supply Voltage Range: 3V to 6V
- I<sup>2</sup>C Programmable Output Voltage: 0.3V to 1.85V
- Maximum Output Current: 5.5A per Phase
- Output Remote Sense for High Accuracy
- Fast Transient Response
- Selectable Automatic Phase Shielding and Power Saving Mode Enables Higher Light Load Efficiency
- Dynamic Voltage Scaling (DVS) with Programmable Slew Rate for Each Output
- Programmable Soft-Start Function
- Interrupt Function and Fault Detection
- Watchdog Function
- Input Under-Voltage Lockout (UVLO)
- Cycle-by-Cycle Current Limit
- Output Under-Voltage Protection
- Over-Temperature Protection
- WQFN-30L 4.5x5 (FC)

## **Simplified Application Circuit**





### **Ordering Information**



#### Note:

#### Richtek products are:

- ▶ RoHS compliant and compatible with the current requirements of IPC/JEDEC J-STD-020.
- ▶ Suitable for use in SnPb or Pb-free soldering processes.

### **Marking Information**

#### RT5800GQWTF-21-01



0W=: Product Code YMDNN: Date Code

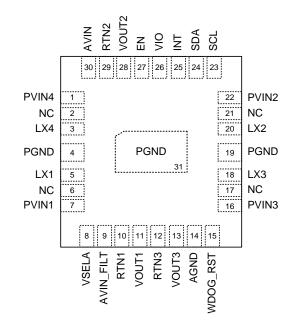
#### RT5800GQWF-22-01



0E=: Product Code YMDNN: Date Code

### **Pin Configuration**

(TOP VIEW)



WQFN-30L 4.5x5 (FC)



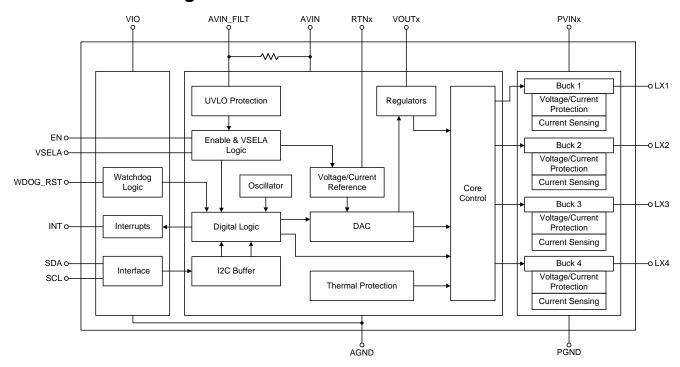
# **Functional Pin Description**

Pin No.	Pin Name	Pin Function
1	PVIN4	Power input for power stage 4. It is recommended to use a $10\mu\text{F}$ , X7R capacitor.
2, 6, 17, 21	NC	No internal connection.
3	LX4	Switching node for power stage 4.
4, 19	PGND	Power ground for power stage.
5	LX1	Switching node for power stage 1.
7	PVIN1	Power input for power stage 1. It is recommended to use a $10\mu\text{F},~\text{X7R}$ capacitor.
8	VSELA	VSEL input pin for all channels. Using corresponding register to define action. "Do Not" leave this pin floating.
9	AVIN_FILT	Filtered analog supply voltage. It is recommended to use a $1\mu\text{F},~\text{X7R}$ capacitor.
10	RTN1	Remote ground sense for Buck1.
11	VOUT1	Output voltage sense for Buck1.
12	RTN3	Remote ground sense for Buck3.
13	VOUT3	Output voltage sense for Buck3.
14	AGND	Analog GND.
15	WDOG_RST	Digital input. Reset all Bucks to default output voltage and some relative registers to default settings when this pin is pulled low. Connect this pin to VIO pin if this pin is not used. "Do Not" leave this pin floating.
16	PVIN3	Power input for power stage 3. It is recommended to use a $10\mu\text{F},~\text{X7R}$ capacitor.
18	LX3	Switching node for power stage 3.
20	LX2	Switching node for power stage 2.
22	PVIN2	Power input for power stage 2. It is recommended to use a $10\mu\text{F}$ , X7R capacitor.
23	SCL	I <sup>2</sup> C clock. "Do Not" leave this pin floating.
24	SDA	I <sup>2</sup> C data. "Do Not" leave this pin floating.
25	INT	Interrupt indicator. When INT function is used, set $0x33[6] = 1$ , $0x34[6] = 1$ and $0x35[6] = 1$ .
26	VIO	I/O supply voltage for digital communications. Connect this pin to 1.8V. "Do Not" leave this pin floating.
27	EN	Master chip enable. A logic-high enables the converter; a logic-low forces the device into shutdown mode. "Do Not" leave this pin floating.
28	VOUT2	Output voltage sense for Buck2.
29	RTN2	Remote ground sense for Buck2.
30	AVIN	Analog input voltage.
31(Exposed PAD)	PGND	Exposed pad. The exposed pad is connected to PGND and must be soldered to a large PCB copper area for maximum power dissipation.

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# **Functional Block Diagram**





### **Operation**

The RT5800 is a power management IC that integrates four high efficiency Buck converters, and is factory configured as a 2/1/1 phase converter. Each of the four converters provides up to 5A output current over an input supply voltage range of 3.3V to 6V.

The RT5800 utilizes the proprietary Advanced Constant On-Time (ACOT<sup>TM</sup>) control architecture. The ultrafast ACOT<sup>TM</sup> control enables the use of small ceramic capacitors (MLCC) to save the PCB size.

During normal operation, the internal high-side power switch (HSFET) is turned on for a fixed interval determined by a one-shot timer at the beginning of each clock cycle. When the HSFET is turned off, the internal low-side power switch (LSFET) is turned on. The output voltage is sensed remotely at VOUTx and RTNx for high accuracy and is compared to an internal reference voltage. Hence, the error signal is obtained and internally compensated. The compensated error signal is then compared to an internal ramp signal. When the minimum off-time one-shot (100ns, max.) has timed out and the inductor current is below the current limit threshold, the one-shot is triggered again if the internal ramp signal falls below the compensated error signal. The ACOT<sup>TM</sup> control architecture features ultrafast transient response. When a load is suddenly increased, the output voltage drops quickly, and triggers a new on-time to rise inductor current again.

#### **Dynamic Voltage Scaling (DVS)**

The RT5800 provides wide output voltage range with 8-bits resolution and each Buck converter has two independently programmable voltage setting. They are called DVS0 and DVS1. Take Buck1 as two-phase configuration for an example, register 0x48[8:0] can set voltage of DVS0 while 0x4A[8:0] is used to set voltage of DVS1. There are two methods to select the DVS. For the first method, it can be changed by software from 0x52[1:0]. Control DVS0 by 0x52[1:0]=00 and DVS1 by setting 0x52[1:0]=01. For the second method, selecting the DVS can be from external hardware pin when setting 0x52[1:0]=10. VSELA pin can be this role and its polarity is defined by 0x52[2]. When setting 0x52[2]=0, pull VSELA high to let DVS0 be used and pull VSELA low to let DVS1 be used. Conversely, when setting 0x52[2]=1, pull VSELA high to let DVS1 be used and pull VSELA low to let DVS0 be used.

The RT5800 also supports DVS speed configuration, whether the slew rate of voltage changing in the same DVSx or between DVS0 and DVS1. Take Buck1 as two-phase configuration for an example, when output voltage is set from low to high or high to low, register 0x54[6:4] defines slew rate of DVS up while 0x54[2:0] is used to define slew rate of DVS down. In order to have better performance during voltage changing operation, the master/slave enters PWM operation and keeps 200µs after the voltage achieves target even when IC is set to Auto mode. Figure 1 and Figure 2 show the DVS up and down operation.

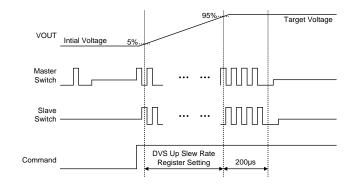


Figure 1. DVS Up Operation

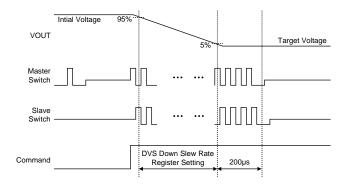


Figure 2. DVS Down Operation

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#### **MODE Selection**

Whether it is DVS0 or DVS1, there are two modes of operation: forced continuous conduction mode (FCCM) and automatic power saving mode (Auto mode). It is set in the following registers: 0x49[5], 0x4B[5], 0x63[5], 0x65[5], 0x7D[5] and 0x7F[5]. For example, to set DVS0 of Buck1 to FCCM, just write "1" at 0x49[5].

#### Auto Mode with Automatically Phase Adding/Shedding

Auto mode enables high efficiency at light load. At low load current, the inductor current can drop to zero and become negative. This is detected by internal zero current-detect circuitry which utilizing the LSFET R<sub>DS(ON)</sub> to sense the inductor current. The LSFET is turned off when the inductor current drops to zero, resulting in discontinuous operation (DCM). Both HSFET and LSFET remain off with the output capacitor supplying the load current until the feedback voltage falls below the feedback reference voltage. DCM operation maintains high efficiency at light load, while setting MODE to Forced PWM (FCCM) operation helps meet tight voltage regulation accuracy requirements. For multiphase outputs, the RT5800 automatically increases the number of operating phases as the load continues to increase above 3A (typ). The two phases are interleaved with 180 degrees apart. Interleaving reduces ripple current at the input and output. Therefore, the input and output capacitors are also reduced. Conversely, when the load current per phase drops below 2.6A (typ), the RT5800 automatically sheds the number of phases.

#### **FCCM Mode**

Setting MODE to Forced PWM (FCCM) operation helps meet stringent voltage regulation accuracy requirements. Users must enable all the set outputs before setting into the FCCM.

#### **UVLO, Enable Control and Soft-Start**

The RT5800 implements under-voltage lockout protection (UVLO) to prevent operation without fully turn on the internal HSFET and LSFET. The UVLO monitors the voltage of AVIN. When the AVIN voltage is lower than UVLO threshold, IC stops switching and resets all digital functions.

The RT5800 provides an EN pin, as an external chip

enable control, to enable or disable the device. If V<sub>EN</sub> is held below a logic-low threshold voltage (VENL) of the enable input (EN), the converter will enter into shutdown mode and reset all digital function (I<sup>2</sup>C), that is, the converter is disabled even if the VIN voltage is above VIN under-voltage lockout threshold (VUVLO). During shutdown mode, the supply current can be reduced to Ishdn (20μA or below). If the EN voltage rises above the logic-high threshold voltage (VENH), the device starts switching. When appropriate voltages are present on the VIN, AVIN, VIO and EN pins, the RT5800 will begin digital function, switching and initiate a soft-start ramp of the output voltage. After the device is turned on and VIO is ready, all digital functions including I<sup>2</sup>C communication start to work in a boot time with 230µs (typ.). The voltage of VIO can be used to supply power to digital function and it is recommend that enable the device after VIO voltage is ready. The RT5800 supports enable delay time setting (factory setting) and soft-start slew rate setting for each Buck. The soft-start function is used to prevent large inrush current while the converter is powered up. Register 0x55[5:4], 0x6F[5:4] and 0x89[5:4] let soft-start time of each be programmable. The start-up sequence is shown in Figure 3. IC also implements enable control by software, it can be set in the registers: 0x49[0], 0x4B[0], 0x63[0], 0x65[0], 0x7D[0] and 0x7F[0]. If the output voltage of Buck is default disable which is only set by factory, the output voltage starts to ramp up by software and the Figure 4 shows the start-up sequence. For disable function, the device supports disable delay time setting (factory setting) by external EN pin and the output voltage ramps down with default discharge resistor. The discharge resistor can be controlled to on or off by register 0x42[0], 0x5F[0] and 0x79[0] when the converter is disabled by software. The power-off sequence is shown in Figure 5 and Figure 6.

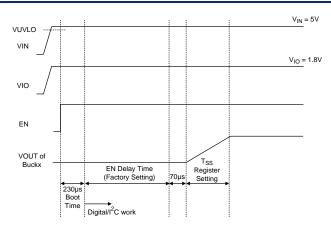


Figure 3. Start-up Sequence

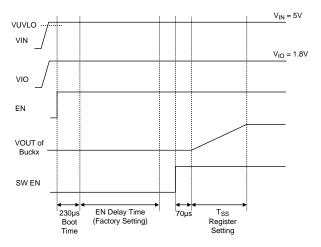


Figure 4. Start-up Sequence by Software

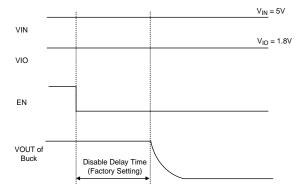


Figure 5. Power-off Sequence

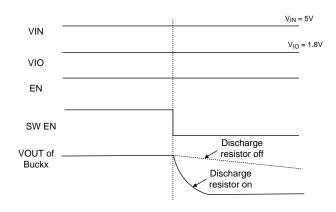


Figure 6. Power-off Sequence by Software

#### **Power Good Indication**

The RT5800 provides a power good indication and this function shows the status of output voltage. When output voltage is between 110% and 90% of setting voltage for each Buck, the PG indication bit goes high. The relative registers are 0x14[7], 0x15[7] and 0x16[7].

#### **Fault Detection and Interrupt Pin**

The RT5800 alerts the host when a warning, like Boot and Hot Die, or fault events, like over-voltage, under-voltage and over-temperature conditions have occurred. Registers 0x13, 0x14, 0x15 and 0x16 can help host to know if the fault or waning event happens. These bits relative to events can be read and cleared. Moreover, the RT5800 provides an interrupt pin with the push-pull output capability and this pin shows these events by using active low. When INT function is used, set 0x33[6] = 1, 0x34[6] = 1 and 0x35[6] = 1. The pull high output voltage of INT pin will be VIO voltage. Register 0x32, 0x33, 0x34 and 0x35 can also set the mask function to mask or pass the event flag output to external interrupt pin. The overall detection function is shown in Figure 7.

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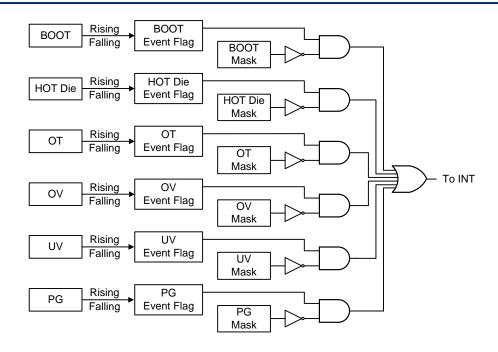


Figure 7. Overall Detection Function

#### **Watchdog Function**

The RT5800 implements a watchdog function which resets some relative registers, like the output voltage, to default settings. Register 0x25 can enable or disable watchdog function of each Buck and provide the debounce time for selection. The operation of watchdog reset is shown in Figure 8. Table 1 shows the registers will be reset when WDOG\_RST pin is pulled low. The I<sup>2</sup>C command needs to be after the WDOG\_RST pull high.

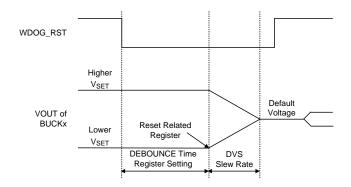


Figure 8. Watchdog Reset Operation

Table 1. Watchdog Reset Register

BUCK1_WDT	BUCK2_WDT	BUCK3_WDT			
0x48	0x62	0x7C			
0x49[0]	0x63[0]	0x7D[0]			
0x4A	0x64	0x7E			
0x4B[0]	0x65[0]	0x7F[0]			
0x52	0x6C	0x86			

#### **The Over-Current Protection**

The RT5800 features cycle-by-cycle current-limit protection on both HSFET and LSFET to prevent the device from the catastrophic damage in output short-circuit, over-current or inductor saturation conditions.

The HSFET over-current protection is achieved by an internal current comparator that monitors the current in the HSFET during each on-time. The switch current is compared with the HSFET peak-current limit (I<sub>LIM\_H</sub>) after a certain amount of delay when the HSFET is turned on each cycle. If an over-current condition occurs, the converter will immediately turn off the HSFET and turn on the LSFET to prevent the inductor current from exceeding the HSFET current limit.

The LSFET over-current protection is achieved by measuring the inductor current through the LSFET



during the LSFET on-time. Once the current rises above the LSFET valley current limit (I<sub>LIM\_L</sub>), the on-time one-shot will be inhibited until the inductor current ramps down to the current limit level (I<sub>LIM\_L</sub>), that is, another on-time can only be triggered when the inductor current goes below the LSFET current limit. If the output load current exceeds the available inductor current (clamped by the LSFET current limit), the output capacitor needs to supply the extra current so that the output voltage will begin to drop. If it drops below the output under-voltage protection trip threshold, the IC will stop switching to avoid excessive heat.

#### **Output Under-Voltage Protection**

The RT5800 includes output under-voltage protection (UVP) against over-load or short-circuited condition by constantly monitoring the output voltage V<sub>OUT</sub>. If V<sub>OUT</sub> drops below the under-voltage protection trip threshold (typically 50% of the internal reference voltage), both HSFET and LSFET will stop switching. Register 0x37[3], 0x38[3] and 0x39[3] can select hiccup or latch protection behavior of each Buck converter when converter is in UV condition. For hiccup behavior, both HSFET and LSFET keep low state in a 1ms and then IC starts to switch. If the output voltage is not greater than UV threshold after internal soft-start end signal is triggered, both HSFET and LSFET will still keep low

state again for next cycle. When each Buck is set to latch mode, UVP will let converter enter shutdown mode unless resetting IC by external EN pin or falling to UVLO low threshold.

#### **Over-Temperature Protection**

The RT5800 includes an over-temperature protection (OTP) circuitry to prevent overheating due to excessive power dissipation. The OTP shuts down switching operation when junction temperature exceeds a thermal shutdown threshold  $T_{SD}$ . Once the junction temperature cools down by a thermal shutdown hysteresis ( $\Delta T_{SD}$ ), the IC resumes normal operation with a complete soft-start. It can select not to shut down IC when OTP happens by using register 0x30[3].

Note that the over temperature protection is intended to protect the device during momentary overload conditions. The protection is activated outside of the absolute maximum range of operation as a secondary fail-safe and therefore should not be relied upon operationally. Continuous operation above specified absolute maximum operating junction temperature may impair device reliability permanently damage the device.



Absolute Maximum Ratings (Note 1)	
Supply Input Voltage	-0.3V to 6.5V
LX Pin Switch Voltage	-0.3V to 7.3V
< 100ns	-5V to 9V
Other I/O Pin Voltages	-0.3V to 7.3V
<ul> <li>Power Dissipation, P<sub>D</sub> @ T<sub>A</sub> = 25°C</li> </ul>	
WQFN-30L 4.5x5 (FC)	2.87W
Package Thermal Resistance (Note 2)	
WQFN-30L 4.5x5 (FC), $\theta_{JA}$	34.8°C/W
WQFN-30L 4.5x5 (FC), $\theta$ JC(Top)	18.2°C/W
WQFN-30L 4.5x5 (FC), $\theta_{JB}$	13.2°C/W
Lead Temperature (Soldering, 10 sec.)	260°C
Junction Temperature	150°C
Storage Temperature Range	−65°C to 150°C
• ESD Susceptibility (Note 3)	
HBM (Human Body Model)	2kV
Pacammandad Operating Conditions (Note 4)	
Recommended Operating Conditions (Note 4)	0.01/15.01/
Supply Input Voltage (for 2 + 2 application)	3.3V to 6V

• Supply Input Voltage (for 2 + 1 + 1 application)----- 3V to 6V

 $\bullet \ \ \mbox{Junction Temperature Range} \ ----- \ \ -40^{\circ}\mbox{C to } 125^{\circ}\mbox{C}$ 

### **Electrical Characteristics**

(VIN = 3.7V,  $T_J = 25^{\circ}C$ , unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Analog Input Voltage	V <sub>AVIN</sub>	For 2 + 2 application	3.3	-	6	V
Power Input Voltage	VPVIN	For 2 + 2 application	3.3	ŀ	6	V
Shutdown Current	I <sub>SHDN</sub>	EN = 0V, Digital circuit doesn't work		1	20	μΑ
Buck Off Current	I <sub>SDBO</sub>	EN = VIO = 1.8V, disable all Buck by software		20	80	μΑ
1Phase no Switching Current	ISLP	Vout = 1.2 x Vout_setting		70	120	μА
Under-Voltage Lockout Threshold	V <sub>UVLO</sub>	V <sub>IN</sub> rising	2.1	2.32	2.45	V
Under-Voltage Lockout Hysteresis	ΔVυνιο			300		mV
High-Side Switch-On Resistance	R <sub>DS(ON)</sub> _H	VIN = 5V	18	25	45	mΩ
Low-Side Switch-On Resistance	R <sub>DS(ON)</sub> _L	V <sub>IN</sub> = 5V	8	15	25	mΩ





Parame	eter	Symbol	Test Conditions	Min	Тур	Max	Unit
SDA, SCL,	Logic-High	ViH	$3V \le V_{IN} \le 6V$	0.7 x VIO			.,
VSELA, WDOG_RST	Logic-Low	VIL	$3V \le V_{IN} \le 6V$			0.3 x VIO	V
EN Throchold	Logic-High	V <sub>ENH</sub>		1.2			V
EN Threshold	Logic-Low	VENL				0.4	V
External Supply I/O Pin	Voltage for	VIN_I/O		1.7	1.8	2.45	V
Vout DC Accur	201		Auto PFM/PWM, V <sub>OUT</sub> = 1V (Note 5)	-2.5	-	2.5	%
VOUT DC ACCUI	acy		Forced PWM, 0.6V ≤ V <sub>OUT</sub> ≤ 1.85V	-1.5		1.5	%
Load Regulation	า	$\Delta V_{LOAD}$	I <sub>OUT(DC)</sub> = 1 to 5A (Note 5)	ı	-0.08		%/A
Line Regulation		$\Delta V$ LINE	$3V \le V_{IN} \le 6V$ , $I_{OUT(DC)} = 1.5A$ (Note 5)		0.2		%/V
Load Transient	Response		2phase operation, 0.1 to 4A, $t_R$ = $t_F$ = 1 $\mu$ s, L = 0.33 $\mu$ H, C <sub>OUT</sub> = 44 $\mu$ F/phase (Note 5)	-	±40		mV
	·		1phase operation, 0.1 to 2A, $t_R = t_F = 1\mu s$ , L= 0.33 $\mu$ H, $C_{OUT} = 44\mu$ F/phase (Note 5)		±40		mV
Line Transient F	Response		$4V \text{ to } 5V, t_R = t_F = 10 \mu s$ (Note 5)		±40		mV
Current Balance			Load = 10A,  I <sub>Avg</sub> - I <sub>LX_1</sub> or 4			0.5	Α
Phase Adding L	.evel		From 1phase to 2phase (Note 5)		3		Α
Phase Shedding	g Level		From 2phase to 1phase (Note 5)		2.6		Α
Soft-Start Time		Tstart	Slew Rate = 10mV/μs	-20		20	%
High-Side Switc Limit per Chann		I <sub>LIM_H</sub>		5.8	8	11	Α
Low-Side Switc Limit per Chann		I <sub>LIM_L</sub>		5.1	7	9	Α
Thermal Shutdo	own	T <sub>SD</sub>			160		°C
Thermal Shutdo Hysteresis	own	$\Delta T_{SD}$			30		°C
HOT Die Warni	ng		0xAA = 0x02 (Note 5)		109		°C
HOT Die Hyster	esis	THYSHD	(Note 5)		15		°C
Discharge Resis	stor			70	115	180	Ω
0		V <sub>UVP_T</sub>	Trigger Level	40	50	60	%
Output UVP Fla	g	V <sub>UVP_R</sub>	Recovery Level		57		%
0.45.40075.5	_	V <sub>OVP_T</sub>	Trigger Level	123	133	143	%
Output OVP Fla	ıg	V <sub>OVP_R</sub>	Recovery Level		125		%
Switching Frequ	iency	fsw	Vout = 1V	1850	2100	2500	kHz



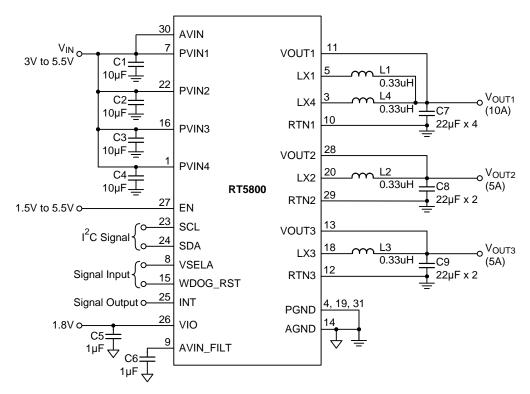
Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Error Rate of DVS Slew Rate		$V_{IN} = 3.7V$ , $V_{OUT} = 0.6V$ to 1.2V	-20	1	20	%
Digital Output Pin : INT		Output low level, ISOURCE = 2mA	I	ı	0.4	V
Digital Output Fill . IIVI		Push-pull, I <sub>SINK</sub> = 2mA	1.6		VIO	V
Digital Output Pin : SDA		Output low level Resistor	-		40	Ω
I <sup>2</sup> C Speed					3.4	MHz
Hold Time (Repeated) Start Condition. After this Period, the First Clock Pulse is Generated	thd;STA	Fast mode (Note5)	0.6			μѕ
Low Period of the SCL Clock	tLOW	Fast mode (Note5)	1.3			μS
High Period of the SCL Clock	tнісн	Fast mode (Note5)	0.6	1		μS
Set-Up Time for a Repeated START Condition	tsu;sta	Fast mode (Note5)	0.6			μS
Data Hold Time	t <sub>HD;DAT</sub>	Fast mode (Note5)	0		0.9	μS
Data Set-Up Time	tsu;dat	Fast mode (Note5)	100			ns
Set-Up Time for STOP Condition	tsu;sto	Fast mode (Note5)	0.6			μS
Bus Free Time between a STOP and START Condition	t <sub>BUF</sub>	Fast mode (Note5)	1.3	1		μS
Rising Time of both SDA and SCL Signals	t <sub>R</sub>	Fast mode (Note5)	20	-1	300	ns
Falling Time of both SDA and SCL Signals	t <sub>F</sub>	Fast mode (Note5)	20		300	ns
SDA Output Low Sink Current	I <sub>OL</sub>	SDA Voltage = 0.4V (Note5)	2			mA
Detect SDA Low Timeout	t <sub>TIMEOUT</sub>	Fast/High speed mode (Note5)		30		ms

- **Note 1.** Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions may affect device reliability.
- Note 2.  $\theta_{JA}$  is measured in the natural convection at  $T_A = 25$ °C on a Four-layer Richtek Evaluation Board.  $\theta_{JC}$  is measured at the top of the package.
- $\mbox{\bf Note 3.}$  Devices are ESD sensitive. Handling precaution is recommended.
- **Note 4.** The device is not guaranteed to function outside its operating conditions.
- $\textbf{Note 5.} \ \textbf{Guaranteed by design}.$

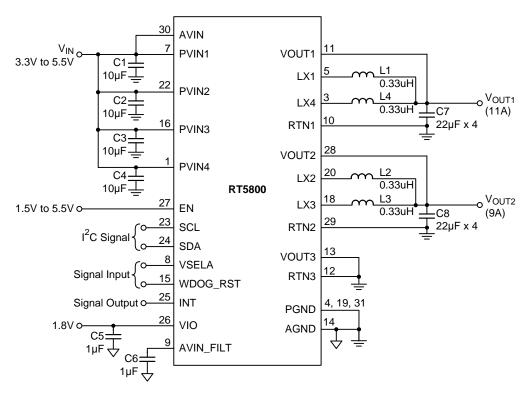


### **Typical Application Circuit**

#### 2 + 1 + 1 Phase



#### 2 + 2 Phase



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#### Table 2. Recommended BOM

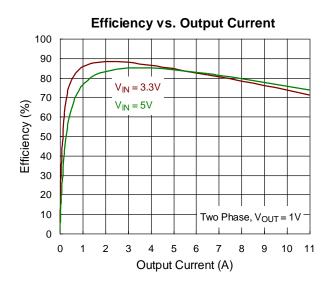
Reference	Qty	Part number	Description	Package	Manufacture
U1	1	RT5800	DC-DC Converter	WQFN-30L 4.5x5 (FC)	RICHTEK
C1, C2, C3, C4	4	GRT188C81A106ME	10μF	C-0603	Murata
C5, C6	2	GRT188C8YA105KE	1μF	C-0603	Murata
C7, C8, C9	8	GRT31CR70J226KE	22μF	C-1206	Murata
L1, L2, L3, L4	4	VCTA25201B-R33MS6	0.33μΗ	2520	Cyntec

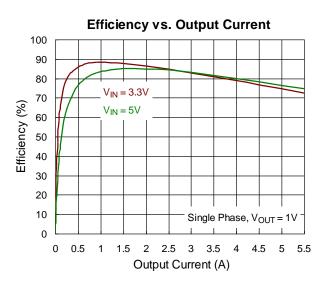
#### Note:

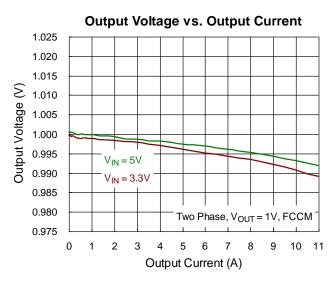
- (1)  $C_{OUT} = 44 \mu F$  per-phase is min. value for the RT5800.
- (2) All the input and output capacitors are the suggested values, referring to the effective capacitances, subject to any de-rating effect, like a DC bias.

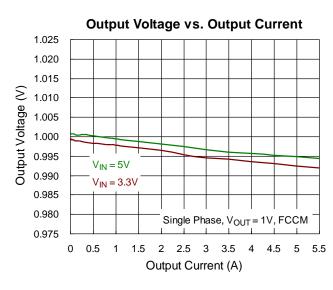


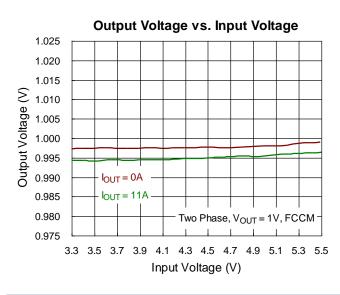
### **Typical Operating Characteristics**

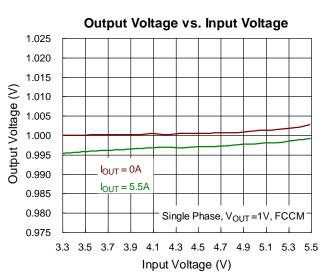






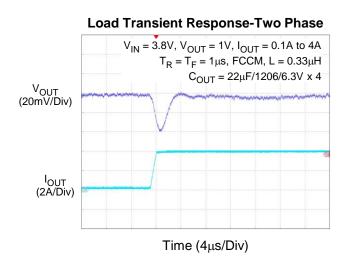


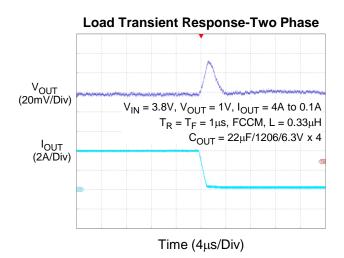


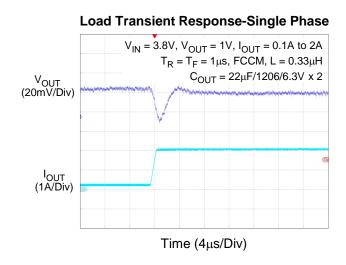


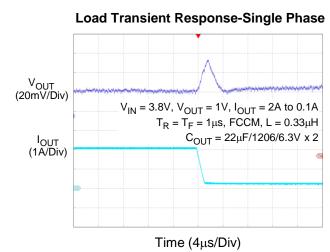
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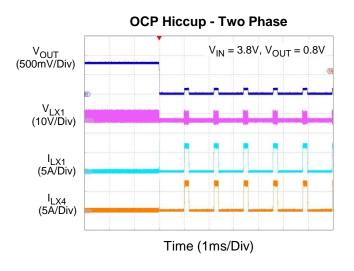


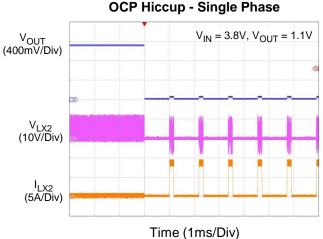




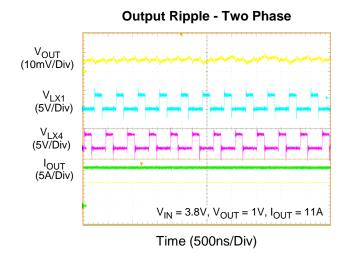


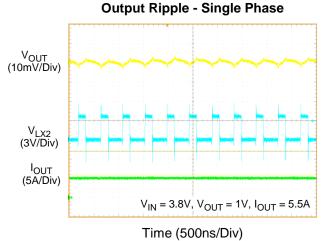


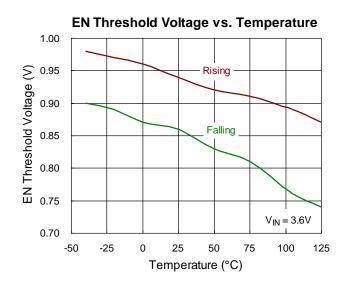


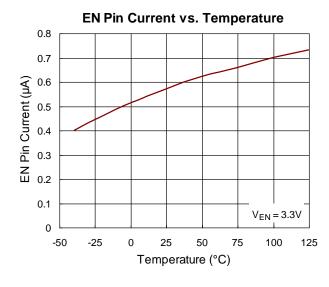


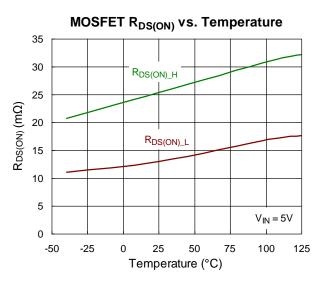


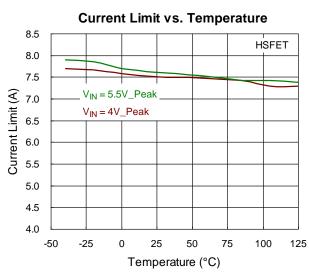














### **Application Information**

The RT5800 is a power management IC that integrates four high efficiency Buck converters, and is factory configured as a 2/1/1 phase converter.

#### **Inductor Selection**

The inductor selection trade-offs among size, cost, efficiency, and transient response requirements. Generally, three key inductor parameters are specified for operation with the device: inductance value (L), inductor saturation current (ISAT), and DC resistance (DCR).

A good compromise between size and loss is a 30% peak-to-peak ripple current to the IC rated current, but it still depends on size consideration. The inductor used in the typical application circuit of datasheet is recommended. The switching frequency, input voltage, output voltage, and selected inductor ripple current determines the inductor value as follows:

$$L = \frac{V_{OUT} \times (V_{IN} - V_{OUT})}{V_{IN} \times f_{SW} \times \Delta I_{I}}$$

To enhance the efficiency, choose a low-loss inductor having the lowest possible DC resistance that fits in the allotted dimensions. The selected inductor should have a saturation current rating greater than the peak current limit of the device. The core must be large enough not to saturate at the peak inductor current (I<sub>L\_PEAK</sub>):

$$\begin{split} \Delta I_{L} &= \frac{V_{OUT} \times (V_{IN} - V_{OUT})}{V_{IN} \times f_{SW} \times L} \\ I_{L\_PEAK} &= I_{OUT\_MAX} + \frac{1}{2} \Delta I_{L} \end{split}$$

The current flowing through the inductor is the inductor ripple current plus the output current. During power up, faults, or transient load conditions, the inductor current can increase above the calculated peak inductor current level calculated above. In transient conditions, the inductor current can increase up to the switch current limit of the device. For this reason, the most conservative approach is to specify an inductor with a saturation current rating equal to or greater than the switch current limit rather than the peak inductor current.

#### **Input Capacitor Selection**

Input capacitance,  $C_{\text{IN}}$ , is needed to filter the pulsating current at the drain of the HSFET. The  $C_{\text{IN}}$  should be sized to do this without causing a large variation in input voltage. Several capacitors may also be paralleled to meet size, height and thermal requirements in the design. For low input voltage applications, sufficient bulk input capacitance is needed to minimize transient effects during output load changes.

The input capacitor should be placed as close as possible to each VIN pin with a low inductance connection to the PGND of the IC. It is recommended to connect capacitors between the VIN pin and the PGND pin for 2.1MHz switching frequency as shown in the typical application circuit. The larger input capacitance is required when a lower switching frequency is used. The X7R capacitors recommended performance for best across temperature and input voltage variations.

#### **Output Capacitor Selection**

The selection of  $C_{OUT}$  is determined by considering to satisfy the voltage ripple and the transient loads. The peak-to-peak output ripple,  $\Delta V_{OUT}$ , is determined by :

$$\Delta V_{OUT} = \Delta I_{L} \left( \text{ESR} + \frac{1}{8 \times C_{OUT} \times F_{SW}} \right)$$

where the  $\Delta I_L$  is the peak-to-peak inductor ripple current. The highest output ripple is at maximum input voltage since  $\Delta I_L$  increases with input voltage. Multiple capacitors placed in parallel may be needed to meet the ESR and RMS current handling requirements.

Ceramic capacitors have very low equivalent series resistance (ESR) and provide the best ripple performance. The X7R dielectric capacitor is recommended for the best performance across temperature and input voltage variations. The variation of the capacitance value with temperature, DC bias voltage and switching frequency needs to be taken into consideration. For example, the capacitance value of a capacitor decreases as the DC bias across the capacitor increases. Be careful to consider the voltage



coefficient of ceramic capacitors when choosing the value and case size. Most ceramic capacitors lose 50% or more of their rated values when used near their rated voltage.

Transient performance can be improved with a higher value output capacitor. Increasing the output capacitance will also decrease the output voltage ripple.

The recommended output capacitors are shown in typical application circuit.

#### **Thermal Considerations**

In many applications, the RT5800 does not generate much heat due to its high efficiency and low thermal resistance of its WQFN- 30L 4.5x5 package. However, in applications which the RT5800 runs at a high ambient temperature and high input voltage or high switching frequency, the generated heat may exceed the maximum junction temperature of the part.

The junction temperature should never exceed the absolute maximum junction temperature  $T_{J(MAX)}$ , listed under Absolute Maximum Ratings, to avoid permanent damage to the device. If the junction temperature reaches approximately 150°C, the RT5800 stops switching the power MOSFETs until the temperature cools down by 25°C.

The maximum power dissipation can be calculated by the following formula:

$$P_{D(MAX)} = (T_{J(MAX)} - T_{A}) / \theta_{JA(EFFECTIVE)}$$
 where

 $T_{J(MAX)}$  is the maximum allowed junction temperature of the die. For recommended operating condition specifications, the maximum junction temperature is 125°C.  $T_A$  is the ambient operating temperature,  $\theta_{JA(EFFECTIVE)}$  is the system-level junction to ambient thermal resistance. It can be estimated from thermal modeling or measurements in the system.

The thermal resistance of the device strongly depends on the surrounding PCB layout and can be improved by providing a heat sink of surrounding copper ground. The addition of backside copper with thermal vias, stiffeners, and other enhancements can also help reduce thermal resistance.

Experiments in the Richtek thermal lab show that

simply set  $\theta_{JA(EFFECTIVE)}$  as 110% to 120% of the  $\theta_{JA}$  is reasonable to obtain the allowed  $P_{D(MAX)}$ .

From the efficiency measurement to find the power loss of system and below formula can be used to determine the power loss of IC by removing the loss of inductor including DC loss and AC loss.

Two phase converter power loss:

$$\begin{aligned} &P_{loss} = (V_{lN} \times I_{lN} - V_{OUT} \times I_{OUT}) - ((\frac{I_{OUT}}{2})^2 \times DCR) \times 2 \\ &-P_{core\_loss} \times 2 - (\frac{V_{OUT}^2 \times ACR}{12 \times L^2 \times f_{SW}^2} \times (1 - \frac{V_{OUT}}{V_{lN}})^2) \times 2 \end{aligned}$$

Single phase converter power loss:

$$\begin{split} &P_{loss} = (V_{lN} \times I_{lN} - V_{OUT} \times I_{OUT}) - I_{OUT}^2 \times DCR - P_{core\_loss} \\ &- \frac{V_{OUT}^2 \times ACR}{12 \times L^2 \times f_{SW}^2} \times (1 - \frac{V_{OUT}}{V_{lN}})^2 \end{split}$$

Where

Pcore\_loss and ACR need to be from inductor supplier

Total loss of IC can't be larger than maximum power loss. If the application requires a higher ambient temperature and/or higher switching frequency, care should be taken to reduce the temperature rise of the part by using a heat sink or air flow. Note that the over-temperature protection is intended to protect the device during momentary overload conditions. The protection is activated outside of the absolute maximum range of operation as a secondary fail-safe and therefore should not be relied upon operationally. Continuous operation above the specified absolute maximum operating junction temperature may impair device reliability or permanently damage the device.

#### **Layout Guidelines**

When laying out the printed circuit board, the following checklist should be used to ensure proper operation of the RT5800:

- ► Four-layer or six-layer PCB with maximum ground plane is strongly recommended for good thermal performance.
- Keep the traces of the main current paths wide and short.

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- Place high frequency decoupling capacitor as close as possible to the IC to reduce the loop impedance and minimize switch node ringing.
- Place multiple vias under the device near PVIN and PGND and close to input capacitors to reduce parasitic inductance and improve thermal performance. To keep thermal resistance low, extend the ground plane as much as possible, and add twenty thermal vias under and near the RT5800 to additional ground planes within the circuit board and on the bottom side.
- ▶ The high frequency switching nodes, LX, should be

- as small as possible. Keep analog components away from the LX node.
- ▶ Reduce the area size of the LX exposed copper to reduce the electrically coupling from this voltage.
- Connect the feedback sense network behind via of output capacitor.
- Connect all analog grounds to common node and then connect the common node to the power ground with a single point.

Figure 9 and Figure 10 shows the layout example which includes one two phase converter for Core and one single phase converter for Memory application.

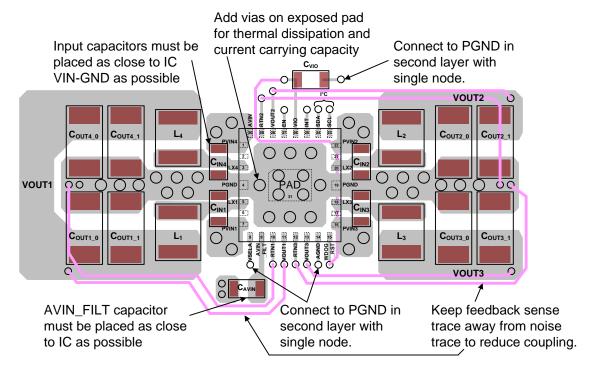


Figure 9. Layout Guideline for 2 + 1 + 1 Application



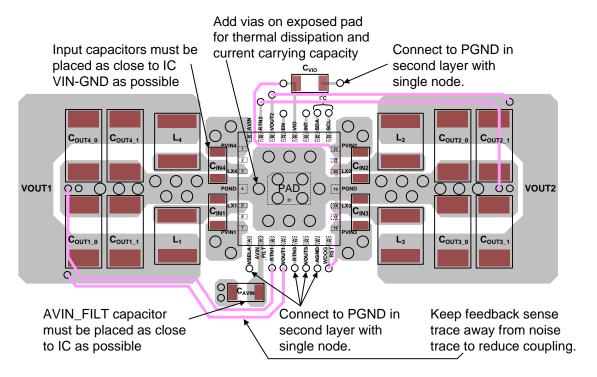


Figure 10. Layout Guideline for 2 + 2 Application



#### I<sup>2</sup>C Interface

The RT5800 I<sup>2</sup>C slave address = 7'b0011000 (Changed by Factory Setting). The RT5800 supports fast mode (bit rate up to 400kb/s). The write or read bit stream (N  $\geq$  1) is shown as Figure 11.

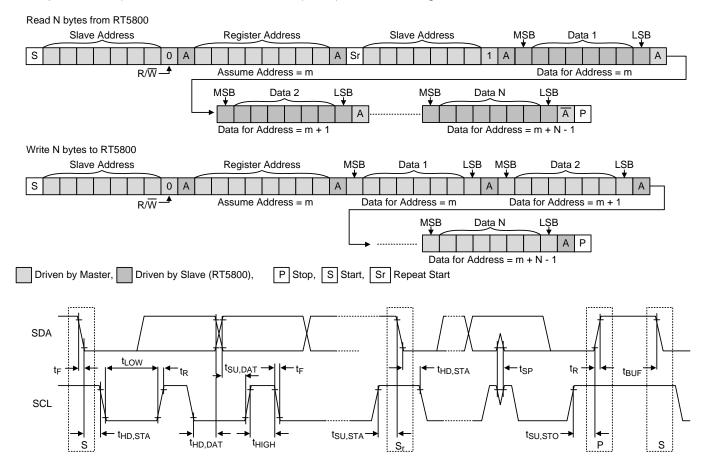


Figure 11. I<sup>2</sup>C Read and Write Stream and Timing Diagram

The RT5800 also supports High-speed mode (bit rate up to 3.4Mb/s) with access code 08H. Figure 12 and Figure 13 show detail transfer format. Hs-mode can only commence after the following conditions (all of which are in F/S-mode):

- ► START condition (S)
- ▶ 8-bit master code (00001xxx)
- ▶ not-acknowledge bit (Ā)

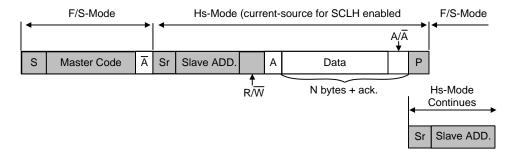


Figure 12. Data Transfer Format in Hs-mode

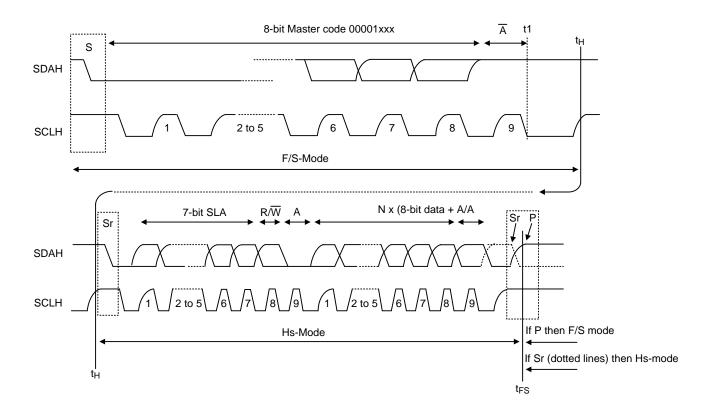


Figure 13. A Complete Hs-mode Transfer



# Table 3. I<sup>2</sup>C Register Summary

Register Address	Register Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Default
0x01	IO_CHIPNA ME				IO_CHI	PNAME				0x01
0x02	IO_CHIPVE RSION				IO_CHIP	VERSION				0x01
0x0A	IO_DIEID3				IO_D	IEID3				0xFE
0x0B	IO_DIEID2		IO_DIEID2							
0x0C	IO_DIEID1		IO_DIEID1							
0x0D	IO_DIEID0		IO_DIEID0							
0x0F	IO_SOFTR ESET			Reserved IO_SO FTRES ET						0x00
0x13	FLT_RECO RDTEMP	FLT_BO OT	Reserved FLT_HO FLT_TE MPSDR Reserved					0x00		
0x14	FLT_RECO RDBUCK1	BUCK1_ PG	Reserved	FLT_BU CK1_OV	FLT_BU CK1_UV		Rese	erved		0x00
0x15	FLT_RECO RDBUCK2	BUCK2_ PG	Reserved	FLT_BU CK2_OV	FLT_BU CK2_UV		Rese	erved		0x00
0x16	FLT_RECO RDBUCK3	BUCK3_ PG	Reserved	FLT_BU CK3_OV	FLT_BU CK3_UV		Rese	erved		0x00
0x22	IO_I2CCFG	Reserved			I	O_I2CADDI	R			0x18
0x25	IO_RSTDV S	Reserved	IO_I	RSTDVS_C	TRL	Reserve	10	O_DBNTIM	IE	0x00
0x30	FLT_OT_ CTRL		Rese	erved		FLT_CT RLOT1		Reserved		0x00
0x32	FLT_MASK TEMP	FLT_MA SKBOOT		Rese	erved		FLT_MA SKHD	FLT_MA SKTSDR	Reserved	0x00
0x33	FLT_MASK BUCK1	FLT_BU CK1MAS KPG	BUCK1 INTACT	FLT_BU CK1MAS KOV	FLT_BU CK1MAS KUV		Rese	erved		0x00
0x34	FLT_MASK BUCK2	FLT_BU CK2MAS KPG	BUCK2 INTACT	FLT_BU CK2MAS KOV	FLT_BU CK2MAS KUV			0x00		
0x35	FLT_MASK BUCK3	FLT_BU CK3MAS KPG	BUCK3 INTACT	FLT_BU CK3MAS KOV	FLT_BU CK3MAS KUV			0x00		
0x37	FLT_BUCK 1_CTRL		Rese	erved		FLT_BU CK1_CT RLUV		Reserved		0x0C



Register Address	Register Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Default	
0x38	FLT_BUCK 2_CTRL		Rese	erved		FLT_BU CK2_CT RLUV		Reserved		0x0C	
0x39	FLT_BUCK 3_CTRL		Rese	erved		FLT_BU CK3_CT RLUV		Reserved		0x0C	
0x3E	BUCK1_ RAMP	Reserved	BUCK1_ DVS_UP		Reserved		BUCK1_ DVS_DO WN	Rese	erved	0x44	
0x42	BUCK1_ CFG0			Reserved BUCK1_ DIS					0x01		
0x48	BUCK1_ DVS0CFG1			T	BUCK <sup>2</sup>	I_DVS0				0x8C	
0x49	BUCK1_ DVS0CFG0	Rese	erved	BUCK1_ DVS0M Reserved BUCK1_ ENDVS0					0x00		
0x4A	BUCK1_ DVS1CFG1		BUCK1_DVS1						0x8C		
0x4B	BUCK1_ DVS1CFG0	Reserved		BUCK1_ DVS1M Reserved ODE					BUCK1_ ENDVS1	0x00	
0x52	BUCK1_ DVSCFG		Reserved  BUCK1_ DVSPIN POL  BUCK1_DVS_ CTRL						0x00		
0x54	BUCK1_ RSPCFG	Reserved	BU	JCK1_RSP	UP	Reserved	BUCK1_RSPDN			0x14	
0x55	BUCK1_ SLEWCTRL	Rese	erved		1_SS_ EW		Rese	erved	ved		
0x5B	BUCK2_ RAMP	Reserved	BUCK2_ DVS_UP		Reserved		BUCK2_ DVS_DO WN	Rese	erved	0x44	
0x5F	BUCK2_ CFG0				Reserved				BUCK2_ DIS	0x01	
0x62	BUCK2_ DVS0CFG1				BUCK2	2_DVS0				0x8C	
0x63	BUCK2_ DVS0CFG0	Rese	erved	BUCK2_ DVS0M ODE		Rese	erved		BUCK2_ ENDVS0	0x00	
0x64	BUCK2_ DVS1CFG1				BUCK	2_DVS1				0x8C	
0x65	BUCK2_ DVS1CFG0	Rese	erved	ved BUCK2_ DVS1M Reserved BUCK2_ ENDVS1						0x00	
0x6C	BUCK2_ DVSCFG			Reserved			BUCK2_ DVSPIN _POL		2_DVS_ RL	0x00	
0x6E	BUCK2_ RSPCFG	Reserved	BL	JCK2_RSP	UP	Reserved	BL	JCK2_RSP	DN	0x14	



Register Address	Register Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Default
0x6F	BUCK2_ SLEWCTRL	Rese	erved	BUCK SLI	2_SS_ EW		Rese	erved		0x00
0x75	BUCK3_ RAMP	Reserved	BUCK3_ DVS_UP		Reserved BUCK3_ DVS_DO Reserved WN					0x44
0x79	BUCK3_ CFG0				Reserved BUCK3_DIS					
0x7C	BUCK3_ DVS0CFG1		BUCK3_DVS0							0x8C
0x7D	BUCK3_ DVS0CFG0	Rese	Reserved BUCK3_DVS0M Reserved ENDVS0						0x00	
0x7E	BUCK3_ DVS1CFG1				BUCK3	3_DVS1				0x8C
0x7F	BUCK3_ DVS1CFG0	Rese	erved	BUCK3_ DVS1M ODE		Rese	erved		BUCK3_ ENDVS1	0x00
0x86	BUCK3_ DVSCFG		Reserved  BUCK3_ DVSPIN POL  BUCK3_DVS_ CTRL					0x00		
0x88	BUCK3_ RSPCFG	Reserved	BU	JCK3_RSPUP Reserved BUCK3_RSPDN			0x14			
0x89	BUCK3_ SLEWCTR	Rese	erved	BUCK SLI	3_SS_ EW		Rese	erved		0x00



# Table 4. I<sup>2</sup>C Register Map

Register Address	0x	01	Register Name						
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
Default	0	0	0	0	0	0	0	1	
Read/Write	R	R	R	R	R	R	R	R	
Bits	Na	Name			Description				
Bit 7 to Bit 0	IO_CHI	PNAME		IO_CHIPNAME					

Register Address	0x	02	Register Name		IO_CHIPVERSION					
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0		
Default	0	0	0	0	0	0	0	1		
Read/Write	R	R	R	R	R	R	R	R		
Bits	Na	me		Description						
Bit 7 to Bit 0	IO_CHIP\	/ERSION		IO_CHIPVERSION						

Register Address	0x	0A	Register Name		IO_DIEID3				
Bits	Bit 7	Bit 6	Bit 5	Bit 4 Bit 3 Bit 2 Bit 1					
Default	1	1	1	1	1	1	1	0	
Read/Write	R	R	R R R R				R	R	
Bits	Na	me			Descr	iption			
Bit 7 to Bit 0	IO_DIEID3			IO_DIEID3					

Register Address	0x	0B	Register Name						
Bits	Bit 7	Bit 6	Bit 5	Bit 4 Bit 3 Bit 2 Bit 1 Bit					
Default	1	1	0	1 1 1 0					
Read/Write	R	R	R	R R R					
Bits	Na	me	Description						
Bit 7 to Bit 0	IO_DIEID2				IO_D	IEID2			

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Register Address	0x0C		Register Name		IO_DIEID1				
Bits	Bit 7	Bit 6	Bit 5	Bit 4 Bit 3 Bit 2 Bit 1					
Default	1	0	1	1	1	0	1	0	
Read/Write	R	R	R	R R R				R	
Bits	Na	me	Description						
Bit 7 to Bit 0	IO_DIEID1				IO_DIEID1				

Register Address	0x0D		Register Name		IO_DIEID0				
Bits	Bit 7	Bit 6	Bit 5	Bit 4 Bit 3 Bit 2 Bit 1				Bit 0	
Default	1	0	0	1	1	0	0	0	
Read/Write	R	R	R	R R R		R	R	R	
Bits	Na	me			Descr	iption			
Bit 7 to Bit 0	IO_DIEID0			IO_DIEID0					

Register Address	0x0F Register Name			IU SUFIRESEI					
Bits	Bit 7	Bit 6	Bit 5	Bit 4 Bit 3 Bit 2 Bit 1 Bi					
Default	0	0	0	0	0	0	0	0	
Read/Write	R	R	R	R R R R RV					
Bits	Na	me			Descr	iption			
Bit 7 to Bit 1	Rese	erved	Reserved b	its					
Bit 0	IO_SOF	TRESET	Reset all digital function to default setting. 0 : Not changed 1 : Reset and bit cleared						



Register Address	0x	13	Register Name		FLT <sub>.</sub>	_RECORDT	EMP	
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Default	0	0	0	0	0	0	0	0
Read/Write	RC	R	R R R RC RC					R
Bits	Na	me			iption			
Bit 7	FLT_I	воот	0 : Boot pro	cess doesn' ocess has oc		N is less thar N is greater t	n UVLO rising han UVLO ri J.	_
Bit 6 to Bit 3 Bit 0	Rese	erved	Reserved b	oits				
Bit 2	FLT_H	OTDIE	Hot die interrupt indicator. Read only and cleared.  0 : Temp of die is lower than threshold.  1 : Die hot. Greater than threshold.					
Bit 1	FLT_TEMPSDR  OT interrupt indicator. Read only and cleared. 0 : No Fault. Less than threshold. 1 : Fault. Greater than threshold or recovery after greater threshold.						er greater tha	เท

Register Address	0x	14	Register Name		FLT_	RECORDBI	JCK1	
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Default	0	0	0 0 0 0 0					0
Read/Write	R	R	RC RC R R					R
Bits	Na	me	Description					
Bit 7	BUCK	(1_PG	0 : VOUT >		tting VOUT	or VOUT < 9 > 90% of set	0% of setting	g VOUT
Bit 6 Bit 3 to Bit 0	Rese	erved	Reserved b	its				
Bit 5	FLT_BU	CK1_OV	OV interrupt indicator. Read only and cleared. 0: No Fault. Less than threshold. 1: Fault. Greater than threshold.					
Bit 4	UV interrupt indicator. Read only and cleared.  FLT_BUCK1_UV  0: No Fault. Greater than threshold.  1: Fault. Less than threshold or recovery after less than threshold.						eshold.	



Register Address	0x	15	Register Name		FLT_	RECORDBI	JCK2	
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Default	0	0	0 0 0 0 0					
Read/Write	R	R	RC RC R R					R
Bits	Na	me			Descr	iption		
Bit 7	BUCK	(2_PG	Power good status indicator.  0: VOUT > 110% of setting VOUT or VOUT < 90% of setting VOUT  1: 110% of setting VOUT > VOUT > 90% of setting VOUT					y VOUT
Bit 6 Bit 3 to Bit 0	Rese	erved	Reserved b	oits				
Bit 5	FLT_BU	OV interrupt indicator. Read only and cleared.  FLT_BUCK2_OV  0 : No Fault. Less than threshold.  1 : Fault. Greater than threshold.						
Bit 4	UV interrupt indicator. Read only and cleared.  FLT_BUCK2_UV  0: No Fault. Greater than threshold.  1: Fault. Less than threshold or recovery after less than threshold.						shold.	

Register Address	0x16 Registe Name			FLT_RECORDBUCK3					
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
Default	0	0	0	0 0 0 0					
Read/Write	R	R	RC RC R R					R	
Bits	Na	me	Description						
Bit 7	BUCK	(3_PG	0 : VOUT >		tting VOUT	or VOUT < 9 > 90% of set	0% of setting	y VOUT	
Bit 6 Bit 3 to Bit 0	Rese	erved	Reserved b	its					
Bit 5	FLT_BU	OV interrupt indicator. Read only and cleared.  BUCK3_OV  0: No Fault. Less than threshold.  1: Fault. Greater than threshold.							
Bit 4	UV interrupt indicator. Read only and cleared.  FLT_BUCK3_UV  0 : No Fault. Greater than threshold.  1 : Fault. Less than threshold or recovery after less than threshold.						shold.		



Register Address	0x22 Register Name				IO_I2CCFG		Bit 0			
Bits	Bit 7	Bit 6	Bit 5	Bit 4 Bit 3 Bit 2 Bit 1				Bit 0		
Default	0	0	0	1	1	0	0	0		
Read/Write	R	R	R	R R R				R		
Bits	Na	me			Descr	iption				
Bit 7	Rese	erved	Reserved bits							
Bit 6 to Bit 0	10_120	ADDR	IO_I2CADE	)R						

Register Address	0x	25	Register Name	IO_RSTDVS					
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
Default	0	0	0	0	0	0	0	0	
Read/Write	R	RW	RW RW R RW RW						
Bits	Na	me			Descr	iption			
Bit 7 and Bit 3	Rese	erved	Reserved b	oits					
Bit 6				able Buck3 w ST pin is pull	•	et function to	o default volt	age when	
Bit 5	IO_RS	STDVS		able Buck2 w ST pin is pull		et function to	o default volt	age when	
Bit 4			Enable/disable Buck1 watchdog reset function to default voltage whe WDOG_RST pin is pulled low.  1 : Enable 0 : Disable						
Bit 2 to Bit 0	IO_DB	NTIME	000 : 0ms ( 001 : 1.56m	ns ms	me 100 : 12.5r 101 : 9ms 110 : 15.25 111 : 14.5m	ms			



Register Address	0x	30	Register Name		F	LT_OT_CTF	RL	
Bits	Bit 7	Bit 6	Bit 5	Bit 5 Bit 4 Bit 3 Bit 2 Bit 1				Bit 0
Default	0	0	0	0	0	0	0	0
Read/Write	R	R	R R RW R R				R	R
Bits	Na	me			Descr	iption		
Bit 7 to Bit 4 Bit 2 to Bit 0	Rese	erved	Reserved b	its				
Bit 3	FLT_C1	TRLOT1	When OT is 0 : Shutdow 1 : Not Shu	vn	ne Buck can	be set to shu	ıtdown or no	t shutdown.

Register Address	0x	32	Register FLT_MASKTEMP					
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Default	0	0	0	0	0	0	0	0
Read/Write	RW	R	R R R RW RW					
Bits	Na	me	Description					
Bit 7	FLT_MA	SKBOOT	Masking the BOOT detection signal. 0: Pass internal logic output to INT pin. 1: Mask internal logic output to INT pin.					
Bit 6 to Bit 3 Bit 0	Rese	erved	Reserved b	its				
Bit 2	FLT_M	ASKHD	Masking the Hot die detection signal. 0 : Pass internal logic output to INT pin. 1 : Mask internal logic output to INT pin.					
Bit 1	FLT_MA	SKTSDR	0 : Pass int	ernal logic o	nutdown dete utput to INT output to INT	pin.		



Register Address	0x	33	Register Name		FLT	Γ_MASKBU(	CK1	
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Default	0	0	0	0	0	0	0	0
Read/Write	RW	RW	RW	RW	R	R	R	R
Bits	Na	me			Descr	iption		
Bit 7	FLT_BUCK	(1MASKPG	0 : Pass int	ernal logic o	good detection utput to INT output to INT	pin.		
Bit 6	BUCK1	INTACT		te this bit to "1" to ensure Buck1 INT function normally. "0" is erved for Richtek internal use only.				
Bit 5	FLT_BUCK	(1MASKOV	0 : Pass int	ernal logic o	Itage detection utput to INT output to INT	pin.		
Bit 4	Masking Buck1 under voltage detection signal.  FLT_BUCK1MASKUV  0 : Pass internal logic output to INT pin.  1 : Mask internal logic output to INT pin.							
Bit 3 to Bit 0	Rese	erved	Reserved b	oits				

Register Address	0x	34	Register Name	ELL MASKBULKZ				
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Default	0	0	0	0	0	0	0	0
Read/Write	RW	RW	RW	RW	R	R	R	R
Bits	Na	me	Description					
Bit 7	FLT_BUCk	(2MASKPG	Masking Buck2 power good detection signal.  O: Pass internal logic output to INT pin.  1: Mask internal logic output to INT pin.					
Bit 6	BUCK2	INTACT			nsure Buck2 ernal use on		normally. "(	)" is
Bit 5	FLT_BUCk	(2MASKOV	0 : Pass int	ernal logic o	Itage detection of the last of	pin.		
Bit 4	FLT_BUCk	(2MASKUV	Masking Buck2 under voltage detection signal.  0 : Pass internal logic output to INT pin.  1 : Mask internal logic output to INT pin.					
Bit 3 to Bit 0	Rese	erved	Reserved b	oits				



Register Address	0x	35	Register Name		FLT	Γ_MASKBU(	CK3		
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
Default	0	0	0	0	0	0	0	0	
Read/Write	RW	RW	RW	RW	R	R	R	R	
Bits	Na	me	Description						
Bit 7	FLT_BUCk	(3MASKPG	0 : Pass int 1 : Mask in	Masking Buck3 power good detection signal. 0 : Pass internal logic output to INT pin. 1 : Mask internal logic output to INT pin.					
Bit 6	BUCK3	INTACT		it to "1" to er r Richtek int			normally. "C	)" is	
Bit 5	FLT_BUCK	(3MASKOV	0 : Pass int	uck3 over vo ernal logic o ternal logic c	utput to INT	pin.			
Bit 4	FLT_BUCK	(3MASKUV	Masking Buck3 under voltage detection signal.  0 : Pass internal logic output to INT pin.  1 : Mask internal logic output to INT pin.						
Bit 3 to Bit 0	Rese	erved	Reserved b	oits					

Register Address	0x	37	Register Name		FLT_BUCK1_CTRL					
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0		
Default	0	0	0	0	1	1	0	0		
Read/Write	R	R	R R RW R R				R			
Bits	Na	me			Descr	iption				
Bit 7 to Bit 4 Bit 2 to Bit 0	Rese	erved	Reserved b	oits						
Bit 3	FLT_B CTR	UCK1_ LUV	Latch or hid 0 : UV Shut 1 : UV Hicc	tdown	on behavior	when Buck1	suffers UV	detection.		

Register Address	0x	38	Register FLT_BUCK2_CTRL					
Bits	Bit 7	Bit 6	Bit 5 Bit 4 Bit 3 Bit 2 Bit 1					Bit 0
Default	0	0	0	0	1	1	0	0
Read/Write	R	R	R R RW R R					
Bits	Na	me	Description					
Bit 7 to Bit 4 Bit 2 to Bit 0	Rese	erved	Reserved b	oits				
Bit 3	FLT_B CTR	UCK2_ LUV	Latch or hiccup protection behavior when Buck2 suffers UV detection: UV Shutdown 1: UV Hiccup					

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Register Address	0x	39	Register Name		FLT	_BUCK3_C	TRL	
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Default	0	0	0	0	1	1	0	0
Read/Write	R	R	R R RW R R					R
Bits	Na	me			Descr	iption		
Bit 7 to Bit 4 Bit 2 to Bit 0	Rese	erved	Reserved b	oits				
Bit 3	FLT_B CTR	UCK3_ LUV	Latch or hic 0 : UV Shut 1 : UV Hicc	tdown	on behavior	when Buck3	suffers UV	detection.

Register Address	0x	0x3E Register Name BUCK1_RAMP						
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Default	0	1	0	0	0	1	0	0
Read/Write	R	RW	R R R RW R R					
Bits	Na	me	Description					
Bit 7 Bit 5 to Bit 3 Bit 1 to Bit 0	Rese	erved	Reserved bits					
Bit 6	BUCK1_	DVS_UP	The operati 0 : Auto Mo 1 : FCCM	ion mode wh ode	en Buck1 ra	mps up.		
Bit 2	BUCK1_D\	The operation mode when Buck1 ramps down.  0 : Decay Mode 1 : FCCM						

Register Address	0x	0x42 Register BUCK1_CFG0						
Bits	Bit 7	Bit 6	Bit 5	Bit 5 Bit 4 Bit 3 Bit 2 Bit 1				
Default	0	0	0	0	0	0	0	1
Read/Write	R	R	R R R R R					
Bits	Na	me	Description					
Bit 7 to Bit 1	Rese	erved	Reserved b	pits				
Bit 0	BUCK	1_DIS	The output discharge resistor operates when Buck1 is turned of software or external enable pin.  0 : Disable output discharge resistor.  1 : Enable output discharge resistor.					



Register Address	0x	48	Register Name		BUC	K1_DVS0C	FG1	
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Default	1	0	0	0	1	1	0	0
Read/Write	RW	RW	RW	RW	RW	RW	RW	RW
Bits	Na	me	Description					
Bit 7 to Bit 0	BUCK1	_DVS0	SEL[7:0] = SEL[7:0] = SEL[7:0] = For 0.3V to	11001000 : ' 0000000 : 0 1.3V, V <sub>OUT</sub>	V <sub>OUT</sub> = 1.85° V <sub>OUT</sub> = 1.3V	L[7:0](decim		x 10mV

Register Address	0x	49	Register BUCK1_DVS0CFG0					
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Default	0	0	0	0	0	0	0	0
Read/Write	R	R	RW R R R RW					
Bits	Na	me	Description					
Bit 7 to Bit 6 Bit 4 to Bit 1	Rese	erved	Reserved b	its				
Bit 5	BUCK1_D	VS0MODE	0 : Auto Mo 1 : FCCM	ode .	mode setting		setting into th	ne FCCM.
Bit 0	BUCK1_	ENDVS0	Enable or disable Buck1 DVS0 0 : Disable 1 : Enable					

Register Address	0x	4A	Register Name	BUCK1_DVS1CFG1					
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
Default	1	0	0	0	1	1	0	0	
Read/Write	RW	RW	RW	RW RW RW RW					
Bits	Na	me		Description					
Bit 7 to Bit 0	BUCK1	_DVS1	SEL[7:0] = SEL[7:0] = SEL[7:0] = For 0.3V to	11001000 : ' 0000000 : 0 1.3V, V <sub>OUT</sub>	$V_{OUT} = 1.85^{\circ}$ $V_{OUT} = 1.3V$ .3V = 0.3V + SE	L[7:0](decim	nal) x 5mV imal) - 200} :	x 10mV	



Register Address	0x	4B	Register Name	SULKI DVSILEGO					
Bits	Bit 7	Bit 6	Bit 5	Bit 4         Bit 3         Bit 2         Bit 1         Bit 0					
Default	0	0	0	0 0 0 0					
Read/Write	R	R	RW R R R RW						
Bits	Na	me		Description					
Bit 7 to Bit 6 Bit 4 to Bit 1	Rese	erved	Reserved b	oits					
Bit 5	BUCK1_D	VS1MODE	0 : Auto Mo 1 : FCCM	ode	mode setting		setting into th	e FCCM.	
Bit 0	BUCK1_	ENDVS1	Note: Please enable all the set outputs before setting into the FCCM.  Enable or disable Buck1 DVS1  0: Disable  1: Enable						

Register Address	0x	:52	Register Name		BU	JCK1_DVSC	FG		
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
Default	0	0	0	0	0	0	0	0	
Read/Write	R	R	R	R R R RW RW R					
Bits	Na	me	Description						
Bit 7 to Bit 3	Rese	erved	Reserved b	eserved bits					
Bit 2		DVSPIN_ OL	external VS 0 : VSELA VSELA 1 : VSELA	•	s bit can def DVS0 setting DVS1 setting DVS1 setting	]	•	-	
Bit 1 to Bit 0	BUCK1_D	VS_CTRL	Buck1 DVS up and down operations are controlled by software or external pin.						



Register Address	0x	54	Register Name	BUCK1_RSPCFG					
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
Default	0	0	0	0 1 0 1 0					
Read/Write	R	RW	RW RW R RW RW RW						
Bits	Na	me	Description						
Bit 7, Bit 3	Rese	erved	Reserved b	oits					
Bit 6 to Bit 4	BUCK1_	_RSPUP		V step/μs step/μs	etting for DV 101 = 2mV s 110 = 1mV s 111 = 0.5m\	step/μs step/μs			
Bit 2 to Bit 0	BUCK1_	_RSPDN	Buck1 DVS 001 = 16m\ 011 = 8mV 100 = 4mV	V step/μs step/μs	etting for DV 101 = 2mV s 110 = 1mV s 111 = 0.5mV	step/μs step/μs			

Register Address	0x	55	Register BUCK1_SLEWCTRL						
Bits	Bit 7	Bit 6	Bit 5	Bit 4 Bit 3 Bit 2 Bit 1 Bit 0					
Default	0	0	0	0	0	0	0	0	
Read/Write	R	R	RW	RW R R R					
Bits	Na	me			Descr	iption			
Bit 7 to Bit 6 Bit 3 to Bit 0	Rese	erved	Reserved b	its					
Bit 5 to Bit 4	BUCK1_S	SS_SLEW	Set the soft-start slew rate when Buck1 is turned on by software or external enable pin. $00 = 10 \text{mV/}\mu\text{s} \qquad 10 = 2.5 \text{mV/}\mu\text{s} \\ 01 = 5 \text{mV/}\mu\text{s} \qquad 11 = 1.25 \text{mV/}\mu\text{s}$						

Register Address	0x	5B	Register Name	BUCK2_RAMP					
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
Default	0	1	0	0 0 0 1 0 0					
Read/Write	R	RW	R	R R R RW R R					
Bits	Na	me		Description					
Bit 7 Bit 5 to Bit 3 Bit 1 to Bit 0	Rese	erved	Reserved b	its					
Bit 6	BUCK2_	DVS_UP	The operati 0 : Auto Mo 1 : FCCM		en Buck2 ra	mps up.			
Bit 2	BUCK2_D	VS_DOWN	The operation mode when Buck2 ramps down.						

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Register Address	0x	5F	Register Name	I BUUKZ UF(50)					
Bits	Bit 7	Bit 6	Bit 5	Bit 4 Bit 3 Bit 2 Bit 1 Bit 0					
Default	0	0	0	0 0 0 0					
Read/Write	R	R	R	R R R RW					
Bits	Na	me			Descr	iption			
Bit 7 to Bit 1	Rese	erved	Reserved b	oits					
Bit 0	BUCK	2_DIS	The output discharge resistor operation when Buck2 is turned off by software or external enable pin.  0: Disable output discharge resistor.  1: Enable output discharge resistor.						

Register Address	0x	62	Register Name	BUCK2_DVS0CFG1						
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0		
Default	1	0	0	0	1	0	0			
Read/Write	RW	RW	RW	RW RW RW RW						
Bits	Na	me		Description						
Bit 7 to Bit 0	BUCK2	2_DVS0	SEL[7:0] = SEL[7:0] = SEL[7:0] = For 0.3V to	11001000 : 0 0000000 : 0 1.3V, V <sub>OUT</sub>	V <sub>OUT</sub> = 1.85° V <sub>OUT</sub> = 1.3V	L[7:0](decim		x 10mV		

Register Address	0x	63	Register Name	BUCK2_DVS0CFG0					
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
Default	0	0	0 0 0 0						
Read/Write	R	R	RW R R R RW						
Bits	Na	me		Description					
Bit 7 to Bit 6 Bit 4 to Bit 1	Rese	erved	Reserved b	its					
Bit 5	BUCK2_D	VS0MODE	0 : Auto Mo 1 : FCCM	ode .	mode setting		etting into th	e FCCM.	
Bit 0	BUCK2_	ENDVS0	Enable or d 0 : Disable 1 : Enable	lisable Buck	2 DVS0				



Register Address	0x	64	Register Name	BUCK/ DVS1CFG1						
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0		
Default	1	0	0	0	1	1	0	0		
Read/Write	RW	RW	RW	RW RW RW RW RW						
Bits	Na	me		Description						
Bit 7 to Bit 0	BUCK2	_DVS1	SEL[7:0] = SEL[7:0] = SEL[7:0] = For 0.3V to	11001000 : ' 0000000 : 0 1.3V, Vоит	V <sub>OUT</sub> = 1.85° V <sub>OUT</sub> = 1.3V	L[7:0](decim	,	x 10mV		

Register Address	0x	65	Register Name	BUCK2_DVS1CFG0					
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
Default	0	0	0 0 0 0 0						
Read/Write	R	R	RW R R R RW						
Bits	Na	me		Description					
Bit 7 to Bit 6 Bit 4 to Bit 1	Rese	erved	Reserved b	oits					
Bit 5	BUCK2_D	VS1MODE	0 : Auto Mo 1 : FCCM	ode .	mode setting		setting into th	ne FCCM.	
Bit 0	BUCK2_	ENDVS1	Note: Please enable all the set outputs before setting into the FCCM.  Enable or disable Buck2 DVS1  0: Disable 1: Enable						



Register Address	0x	6C	Register Name	BUCK2_DVSCFG					
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
Default	0	0	0	0 0 0 0 0					
Read/Write	R	R	R R RW RW R						
Bits	Na	me	Description						
Bit 7 to Bit 3	Rese	erved	Reserved b	Reserved bits					
Bit 2	_	DVSPIN_ OL	external VS 0 : VSELA VSELA 1 : VSELA	SELA pin, thi = 1 => use [ = 0 => use [ = 1 => use [	s bit can defi DVS0 setting DVS1 setting DVS1 setting	ne the polar	controlled by ity for VSEL	•	
Bit 1 to Bit 0	BUCK2_D	VS_CTRL	VSELA = 0 => use DVS0 setting  Buck2 DVS up and down operations are controlled by software external pin.  RL 00 : Use DVS0 setting 01 : Use DVS1 setting 10 : Controlled by VSELA pin						

Register Address	0x	6E	Register Name	BUCK2_RSPCFG					
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
Default	0	0	0	1	0	0			
Read/Write	R	RW	RW	RW RW RW RW RW					
Bits	Na	me		Description					
Bit 7, Bit 3	Rese	erved	Reserved b	oits					
Bit 6 to Bit 4	BUCK2_	_RSPUP	001 = 16m <sup>1</sup>	V step/μs step/μs	etting for DV 101 = 2mV s 110 = 1mV s 111 = 0.5m\	step/μs step/μs			
Bit 2 to Bit 0	BUCK2_	_RSPDN	Buck2 DVS 001 = 16m\ 011 = 8mV 100 = 4mV	V step/μs step/μs	etting for DV 101 = 2mV s 110 = 1mV s 111 = 0.5m\	step/μs step/μs			



Register Address	UXDE		Register Name	SULK/SIEWUIRI					
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
Default	0	0	0	0	0	0	0	0	
Read/Write	R	R	RW	RW	R	R	R	R	
Bits	Na	me			Descr	iption			
Bit 7 to Bit 6 Bit 3 to Bit 0	Rese	erved	Reserved b	oits					
Bit 5 to Bit 4	BUCK2_S	SS_SLEW	Set the soft external en 00 = 10mV/ 01 = 5mV/µ	able pin. /μs       10 =	ate when Bu = 2.5mV/μs = 1.25mV/μs		d on by softw	are or	

Register Address	0x	0x75		BUCK3_RAMP						
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0		
Default	0	1	0	0	0	1	0	0		
Read/Write	R	RW	R	R	R	RW	R	R		
Bits	Name			Description						
Bit 7 Bit 5 to Bit 3 Bit 1 to Bit 0	Rese	erved	Reserved b	its						
Bit 6	BUCK3_	BUCK3_DVS_UP  The ope 0 : Auto 1 : FCCM			en Buck3 ra	mps up.				
Bit 2	BUCK3_D	VS_DOWN	The operation mode when Buck3 ramps down.							

Register Address	0x79		Register Name	BUCK3_CFG0					
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
Default	0	0	0	0	0	0	0	1	
Read/Write	R	R	R	R	R	R	R	RW	
Bits	Name				Descr	iption			
Bit 7 to Bit 1	Rese	erved	Reserved b	bits					
Bit 0	BUCK	3_DIS	software or 0 : Disable	external en output disch	esistor opera able pin. arge resistor arge resistor	·.	uck3 is turne	ed off by	



Register Address	0x	0x7C		BUCK3_DVS0CFG1					
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
Default	1	0	0	0	1	1	0	0	
Read/Write	RW	RW	RW	RW	RW	RW	RW	RW	
Bits	Na	me	Description						
Bit 7 to Bit 0	BUCK3	_DVS0	SEL[7:0] = SEL[7:0] = SEL[7:0] = For 0.3V to	11001000 : 0 0000000 : 0 1.3V, V <sub>OUT</sub>	$V_{OUT} = 1.85^{\circ}$ $V_{OUT} = 1.3V$ .3V = 0.3V + SE	L[7:0](decim	nal) x 5mV imal) - 200} :	x 10mV	

Register Address	0x7D Register Name			BUCK3_DVS0CFG0					
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
Default	0	0	0	0	0	0	0	0	
Read/Write	R	R	RW	R	R	R	R	RW	
Bits	Na	me		Description					
Bit 7 to Bit 6 Bit 4 to Bit 1	Rese	erved	Reserved bits						
Bit 5	BUCK3_D	VS0MODE	Buck3 DVS0 operation mode setting 0 : Auto Mode 1 : FCCM Note : Please enable all the set outputs before setting into the					ne FCCM.	
Bit 0	BUCK3_	ENDVS0	Enable or disable Buck3 DVS0  0 : Disable  1 : Enable						

Register Address	0x7E Register Name			BUCK3_DVS1CFG1				
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
Default	1	0	0	0	1	1	0	0
Read/Write	RW	RW	RW	RW	RW	RW	RW	RW
Bits	Na	me	Description					
Bit 7 to Bit 0	BUCK3	3_DVS1	SEL[7:0] = SEL[7:0] = SEL[7:0] = For 0.3V to	11001000 : ' 0000000 : 0 1.3V, V <sub>OUT</sub>	V <sub>OUT</sub> = 1.85° V <sub>OUT</sub> = 1.3V	L[7:0](decim		x 10mV



Register Address	0x7F Register Name			BUCK3_DVS1CFG0					
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	
Default	0	0	0	0	0	0	0	0	
Read/Write	R	R	RW	R	R	R	R	RW	
Bits	Na	me			Descr	iption			
Bit 7 to Bit 6 Bit 4 to Bit 1	Rese	erved	Reserved bits						
Bit 5	BUCK3_D	VS1MODE	Buck3 DVS1 operation mode setting 0 : Auto Mode 1 : FCCM Note : Please enable all the set outputs before setting into the FCC						
Bit 0	BUCK3_	ENDVS1	Enable or disable Buck3 DVS1  0 : Disable  1 : Enable						

Register Address	0x	86	Register Name	5   BUCK3 DVSCFG						
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0		
Default	0	0	0	0	0	0	0	0		
Read/Write	R	R	R	R	R	RW	RW	RW		
Bits	Na	me			Descr	escription				
Bit 7 to Bit 3	Reserved		Reserved bits							
Bit 2	_	DVSPIN_ OL	external VS 0 : VSELA VSELA 1 : VSELA		ne the polar	controlled by ity for VSEL	•			
Bit 1 to Bit 0	BUCK3_D	VS_CTRL	external pir 00 : Use D\ 01 : Use D\	n. /S0 setting	·	s are controll	led by softwa	are or		

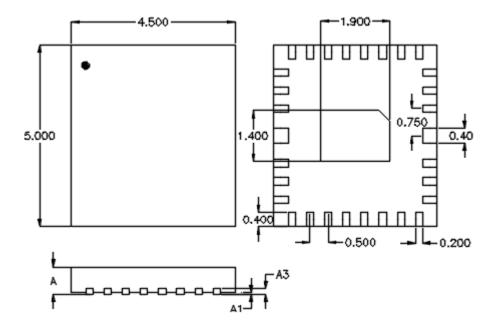


Register Address	0x88		Register Name	BUCK3_RSPCFG					
Bits	Bit 7	Bit 6	Bit 5 Bit 4 Bit 3 Bit 2				Bit 1	Bit 0	
Default	0	0	0	1	0	1	0	0	
Read/Write	R	RW	RW	RW	R	RW	RW	RW	
Bits	Na	me			Descr	iption			
Bit 7, Bit 3	Rese	erved	Reserved bits						
Bit 6 to Bit 4	BUCK3_	_RSPUP		/ step/μs step/μs	etting for DV 101 = 2mV s 110 = 1mV s 111 = 0.5mV	step/μs step/μs			
Bit 2 to Bit 0	BUCK3_	_RSPDN	Buck3 DVS 001 = 16m\ 011 = 8mV 100 = 4mV	/ step/μs step/μs	etting for DV 101 = 2mV s 110 = 1mV s 111 = 0.5m\	step/μs step/μs			

Register Address	0x	89	Register Name	BUCK3_SLEWCTRL						
Bits	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0		
Default	0	0	0	0	0	0	0	0		
Read/Write	R	R	RW	RW	R	R	R	R		
Bits	Name				Descr	iption				
Bit 7 to Bit 6 Bit 3 to Bit 0	Rese	erved	Reserved b	its						
Bit 5 to Bit 4	BUCK3_S	SS_SLEW	Set the soft external en 00 = 10mV/ 01 = 5mV/µ	able pin. ′μs       10 =	ate when Bu = 2.5mV/μs = 1.25mV/μs		d on by softw	are or		



## **Outline Dimension**



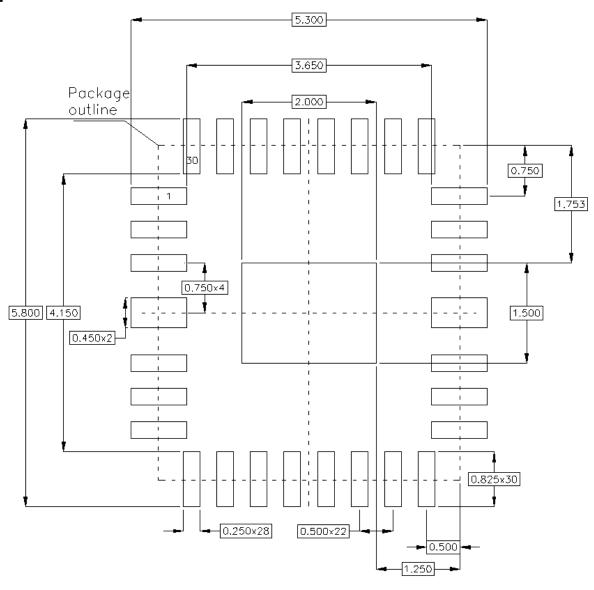
Symbol	Dimensions I	n Millimeters	Dimensions In Inches		
Symbol	Min	Max	Min	Max	
А	0.700	0.800	0.028	0.031	
A1	0.000	0.050	0.000	0.002	
А3	0.175	0.250	0.007	0.010	

Tolerance	
±0.050	

W-Type 30L QFN 4.5x5 (FC) Package



## **Footprint Information**



Package	Number of Pin	Tolerance
V/W/U/XQFN4.5x5-30(FC)	30	±0.05

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